

**1. Scope :**

This specification applies to silicon zener double diodes Flip chips,  
Device NO. SD-51513GF-A

**2. Structure :**

- 2-1. Planar type : PNP, Zener Double Diodes.
- 2-2. Electrodes :  
Top side : SnAu Alloy.  
Back side : Aluminum layer.

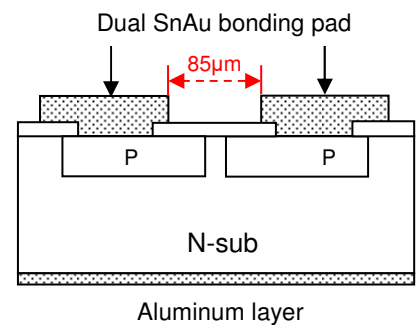
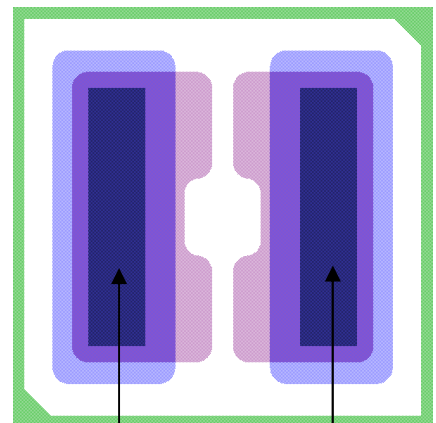
**3. Size :**

- 3-1. \*Chip size : 15.6 mils x 15.6 mils (0.395 mm x 0.395 mm ).
- 3-2. Chip thickness :  $5.9 \pm 1.0$  mils ( $0.150 \pm 0.025$  mm )
- 3-3. Bonding pad : 12.2mils x 4.7 mils (0.310 mm x 0.120 mm).
- 3-4. The distance between dual SnAu bonding pad: 3.3mils (0.085 mm).
- 3-5. Pattern drawing : Refer to the attached drawing.

\*Including scribing line. The chip size is about  $(0.370 \pm 0.015) \times (0.370 \pm 0.015)$  mm<sup>2</sup> after dicing.

**4. Electrical characteristics (Ta = 25 °C)**

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Reverse Leakage Current	$I_R$	$V_R=9V$ $E_e=0mW/cm^2$			100	nA
Zener Voltage	$V_Z$	$I_Z=5mA$ $E_e=0mW/cm^2$	11	13	15	V



Equivalent Circuit

